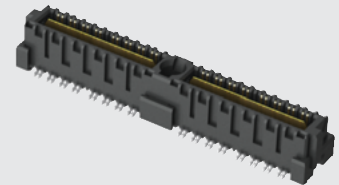


QMS-026-06.75-L-D-A



(0,635 mm) .025"

QMS SERIES

RUGGED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:
Liquid Crystal Polymer
Terminal & Ground Plane Material:
Phosphor Bronze
Plating:
Au over 50µ" (1,27 µm) Ni (Tin on Ground Plane Tail)

Current Rating:
Contact:
2.6 A per pin
(1 pin powered per row)
Ground Plane:
15.7 A per ground plane
(1 ground plane powered)
Voltage Rating:
300 VAC mated with QFS
Operating Temp:
-55°C to +125°C
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity:
(0,10 mm) .004" max (026-052)
(0,15 mm) .006" max (078)
Board Stacking:
For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

Industry Standards

- SUMIT™
- PCI/104-Express™

Protocols Supported

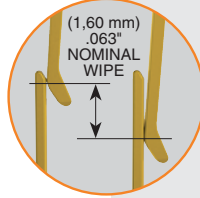
- 100 GbE
- Fibre Channel
- XAUI
- PCI Express®
- SATA

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

Note: Some lengths, styles and options are non-standard, non-returnable.

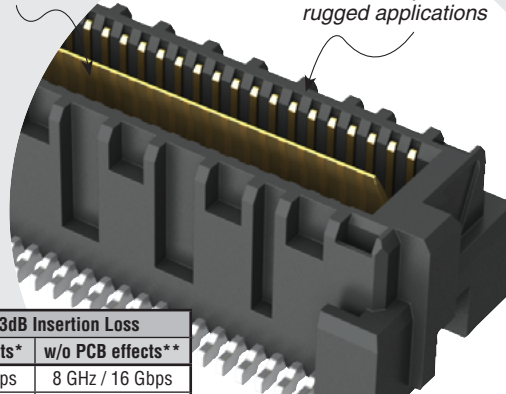
Board Mates:
QFS

Cable Mates:
6QCDC



Integral metal plane for power or ground

Increased insertion depth for rugged applications



QMS/QFS 10 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	8 GHz / 16 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	7.5 GHz / 15 Gbps	9 GHz / 18 Gbps

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.
Performance data for other stack heights and complete test data available at www.samtec.com?QMS or contact sig@samtec.com

Final **inch**
CERTIFIED

ALSO AVAILABLE
(MOQ Required)

- Other platings
 - Guide Posts
 - Without PCB Alignment Pins (05.75 and 06.75 only)
 - Hot Pluggable
 - 64 (-DP) and 104 positions per row
- Contact Samtec.

28+
Gbps

QMS — **PINS PER ROW NO. OF PAIRS** — **LEAD STYLE** — **PLATING OPTION** — **TYPE** — **A** — **OTHER OPTION**

-026, -052, -078
(52 total pins per bank = -D)

-016, -032, -048
(16 pairs per bank = -D-DP)
(-078 & -048 Not available with -09.75 lead style)

Specify **LEAD STYLE** from chart

-L
(-05.75 and -06.75 lead style only)
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

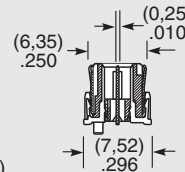
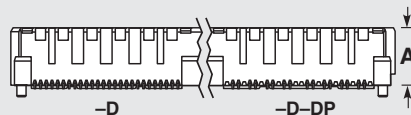
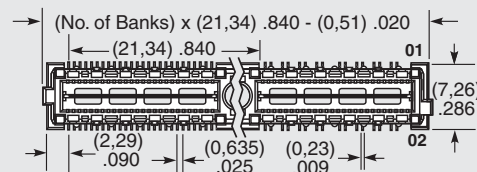
-SL
(-09.75 lead style only)
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

-D
= Single-Ended
-D-DP
= Differential Pair

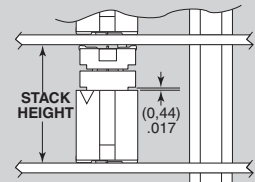
-K
= (5,50 mm) .217" DIA Polyimide film Pick & Place Pad

MATED HEIGHT*			
LEAD STYLE	A	QFS LEAD STYLE	
		-04.25	-06.25
-05.75	(5,38) .212	10 mm	12 mm
-06.75	(6,35) .250	11 mm	13 mm
-09.75	(9,35) .368	14 mm	16 mm

*Processing conditions will affect mated height.



APPLICATION



Requires Standoff SO-1524-03-01-01-L for 15,24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

INDUSTRY STANDARD	INTERCONNECTS			STACK HEIGHT
	TERMINAL	SOCKET	BANKS	
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm